



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

Masahiro Shimada, et al.

Serial No.: 10/747,807 Group Art Unit: Not Yet Assigned

Filing Date: December 30, 2003 Examiner: Unknown

For: WIRING STRUCTURE FOR SEMICONDUCTOR DEVICE

Honorable Commissioner of Patents
Alexandria, Virginia 22313-1450

INFORMATION DISCLOSURE STATEMENT

Sir:

Under the provisions of 37 CFR §1.97 through §1.99 and pursuant to applicant's duty of disclosure under 37 CFR §1.56, applicant respectfully brings the following documents listed on the attached form PTO-1449, to the attention of the Examiner in charge of the above-identified application. Copies of the listed documents are provided herewith for the convenience of the Examiner. In compliance with the concise explanation requirement under 37 CFR §1.98(a)(3), the relevance of these documents is discussed on page 2 of the subject application.

This citation does not constitute an admission that the references are relevant or material to the claims. They are only cited as constituting related art of which the applicant is aware.

It is respectfully requested that the listed references be considered by the Examiner and formally made of record in this application.

Please charge any deficiencies in fees and credit any overpayment of fees to Attorney's Deposit Account No. 50-0481.

Respectfully submitted,

A handwritten signature in black ink, appearing to read "Sean M. McGinn".

Sean M. McGinn
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Date: 7/20/04
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INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Docket Number (Optional)

PTGF-03070

Application Number

10/747,807

Applicant(s)

Masahiro SHIMADA, et al.

Filing Date

December 30, 2003

Group Art Unit

Not Yet Assigned

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

		Kazuhide Abe, et al., "High Reliable Cu Damascene Interconnects with Cu/Ti/TiN/Ti Layered Structure", Oki Technical Review, No. 184, Vol. 67, No. 3, pp. 65-68, October 2000.
		Miki Moriyama, et al., "Future Fabrication Techniques for Cu Wires used in Si ULSI Devices", Material Japan, Vol. 39, No. 11, pp. 901-908 (2000).

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.